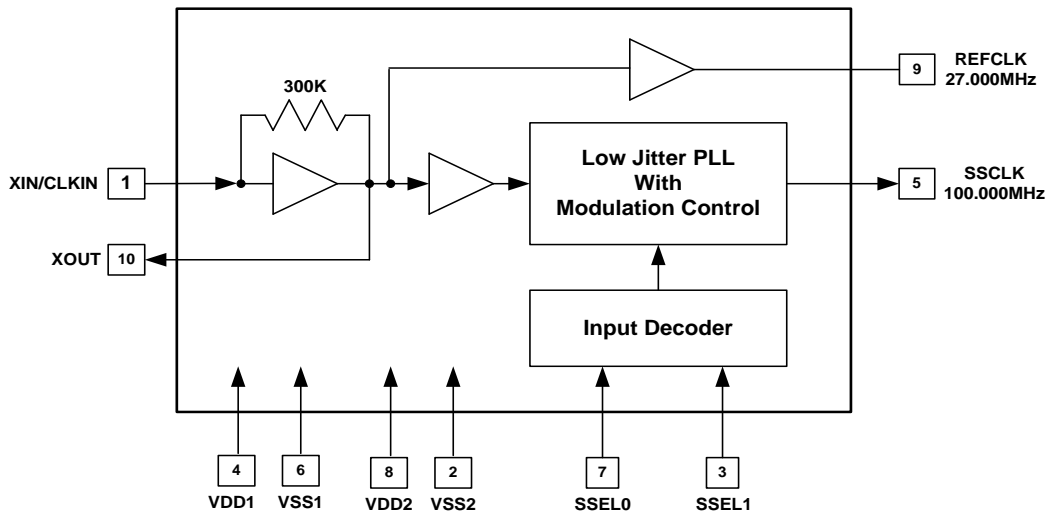


## Low Jitter and Power Clock Generator with SSCG

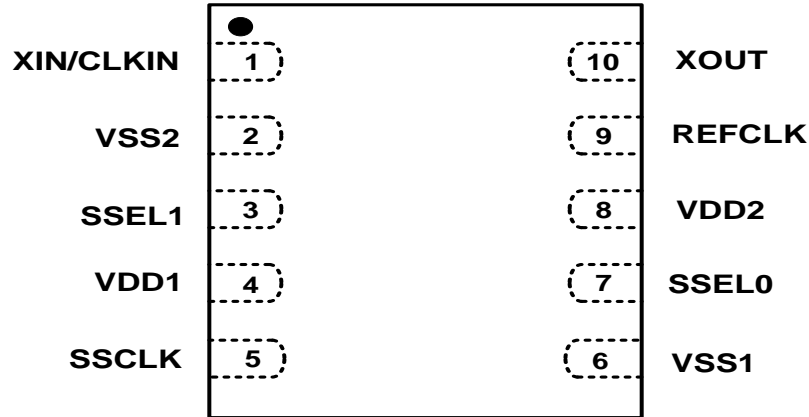
Key Features	Description
<ul style="list-style-type: none"> <li>• Low power dissipation               <ul style="list-style-type: none"> <li>- 13.5mA-typ CL=15pF</li> <li>- 18.0mA-max CL=15pF</li> </ul> </li> <li>• 3.3V +/-10% power supply range</li> <li>• 27.000MHz crystal or clock input</li> <li>• 27.000MHz REFCLK</li> <li>• 100MHz SSCLK with SSEL0/1 spread options</li> <li>• Low CCJ Jitter</li> <li>• Low LT Jitter</li> <li>• Internal Voltage Regulators</li> <li>• 45% to 55% Output Duty Cycle</li> <li>• On-chip Crystal Oscillator</li> <li>• -10 to +85 Temperature Range</li> <li>• 10-pin 3x3x0.75 mm TDFN package</li> </ul>	<p>The SL16010DC is a low power dissipation spread spectrum clock generator using SLI proprietary low jitter PLL. The SL16010DC provides two output clocks. REFCLK (Pin-9) which is a buffered output of the 27.000MHz input crystal and SSCLK (Pin-5) which is synthesized as 100.000MHz nominal by an internal PLL using the 27.00MHz external input crystal or clock.</p> <p>In addition, SSEL0 (Pin-7) and SSEL1 (Pin-3) spread percent selection control inputs enable users to select from 0.0% (no spread) to -3.0% down spread at 100.000MHz SSCLK output to reduce and optimize system EMI levels.</p> <p>The SL16010DC operates in an extended temperature range of -10 to +85°C.</p>
<p><b>Application</b></p> <ul style="list-style-type: none"> <li>• Video Cards</li> <li>• NB and DT PCs</li> <li>• HDTV and DVD-R/W</li> <li>• Routers, Switches and Servers</li> <li>• Data Communications</li> <li>• Embedded Digital Applications</li> </ul>	<p>Contact SLI for other programmable frequencies, Spread Spectrum Clock (SSC) options, as well as 2.5V+/-10 and 1.8V+/-5% power supply options.</p> <p><b>Benefits</b></p> <ul style="list-style-type: none"> <li>• EMI Reduction</li> <li>• Improved Jitter</li> <li>• Low Power Dissipation</li> <li>• Eliminates external Xtals or XOs</li> </ul>

### Block Diagram



**Figure 1. Block Diagram**

**Pin Configuration**



**Figure 2. 10-Pin TDFN (3x3x0.75 mm)**

**Table 1. Pin Description**

Pin Number	Pin Name	Pin Type	Pin Description
1	XIN/CLKIN	Input	External crystal or clock input. Capacitance at this pin is 4 pF-typ.
2	VSS2	Power	Power supply ground for 27.000MHz REFCLK output.
3	SSEL1	Input	SSEL1 spread percent selection pin. Refer to Table 5 for available spread options using SSEL1 pin. Three state, Low (L), Middle (M) and High (H) digital input logic levels. This pin has 150kΩ-typ input pull down resistor.
4	VDD1	Power	Positive power supply for 100.000MHz SSCLK output. 3.3V +/-10%.
5	SSCLK	Output	SSCLK clock output. 100.000MHz nominal. Refer to Table 5 for available spread % options by using SSEL0 and SSEL1 control pins.
6	VSS1	Power	Power supply ground for 100.000MHz SSCLK output.
7	SSEL0	Input	SSEL spread percent selection pin. Refer to Table 5 for available spread options using SSEL0 pin. Three state, Low (L), Middle (M) and High (H) digital input logic levels. This pin has 150kΩ-typ input pull down resistor.
8	VDD2	Power	Positive power supply for 27.000MHz REFCLK output. 3.3V +/-10%.
9	REFCLK	Output	REFCLK clock output. 27.000MHz nominal.
10	XOUT	Output	Crystal output. Capacitance at this pin 4 pF-typ. If clock input is used, leave this pin not connected (N/C).



**Table 2. Absolute Maximum Ratings**

Description	Condition	Min	Max	Unit
Supply voltage, VDD		-0.5	4.2	V
All Inputs and Outputs		-0.5	VDD+0.5	V
Ambient Operating Temperature	In operation, extended C grade	-10	85	°C
Storage Temperature	No power is applied	-65	150	°C
Junction Temperature	In operation, power is applied	-	125	°C
Soldering Temperature		-	260	°C
ESD Rating (Human Body Model)	JEDEC22-A114D	-4,000	4,000	V
ESD Rating (Charge Device Model)	JEDEC22-C101C	-1,500	1,500	V
ESD Rating (Machine Model)	JEDEC22-A115D	-200	200	V

**Table 3. DC Electrical Characteristics (C-Grade)**

Unless otherwise stated VDD= 3.3V+/- 10%, CL=15pF and Ambient Temperature range -10 to +85Deg C

Description	Symbol	Condition	Min	Typ	Max	Unit
Operating Voltage	VDD1/2	VDD1=VDD2=3.3V +/-10%	2.97	3.3	3.63	V
Input Low Voltage	VINL	SSEL0 and SSEL1	0	-	0.2	V
Input Middle Voltage	VINM	SSEL0 and SSEL1	0.4VDD	-	0.6VDD	
Input High Voltage	VINH	SSEL0 and SSEL1	0.9VDD	-	VDD	V
Input High Voltage	VINH1	CMOS Level, Pin-1 If input is clock	0.7VDD	-	VDD	V
Input Low Voltage	VINL1	CMOS Level, Pin-1 If input is clock	0	-	0.3VDD	V
Output Low Voltage	VOL	IOL=15mA, Pins 5 and 9	-	-	0.4	V
Output High Voltage	VOH	IOH=-15mA , Pins 5 and 9	VDD-0.4	-	-	V
Power Supply Current	IDD	SSEL=1, M or 0, CL=15pF, VDD=3.63V and T=85°C	-	13.5	18.0	mA
Input Capacitance	CIN1	XIN and XOUT, Pins 1 and 10	-	4	-	pF
Input Capacitance	CIN2	SSEL0/1, Pins 7 and 3	-	3	5	pF
Load Capacitance	CL	SSCLK and REFCLK, Pins 5 and 9	-	-	15	pF
Pull Down Resistor	RPD		100	150	250	kΩ

**Table 4. AC Electrical Characteristics (C-Grade)**

Unless otherwise stated VDD= 3.3V+/-10%, CL=15pF and Ambient Temperature range -10 to +85 Deg C

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Frequency Range	FR-1	Input crystal or clock range, +/-10 ppm	-	27.000	-	MHz

		crystal accuracy if a crystal is used				
<b>Frequency Range</b>	FR-2	REFCLK, Pin 9	-	27.000	-	MHz
<b>Frequency Range</b>	FR-3	SSCLK, Pin 5	-	100.000	-	MHz
<b>Frequency Accuracy</b>	FACC1	REFCLK, Pin 9	-30	+/-0	30	ppm
<b>Frequency Accuracy</b>	FACC2	SSCLK, Pin 5, SSEL0/1=0	-30	+/-0	30	ppm
<b>Rise and Fall Time</b>	TR/F-1	REFCLK, Pin 9, CL=5pF, measured from 20% to 80% of VDD	-	1.0	1.5	ns
<b>Rise and Fall Time</b>	TR/F-2	REFCLK, Pin 9, CL=15pF, measured from 20% to 80% of VDD	-	1.5	2.0	ns
<b>Rise and Fall Time</b>	TR/F-3	SSCLK, Pin 5, CL=5pF, measured from 20% to 80% of VDD	-	0.75	1.0	ns
<b>Rise and Fall Time</b>	TR/F-4	SSCLK, Pin 5, CL=15pF, measured from 20% to 80% of VDD	-	1.5	1.75	ns
<b>Output Duty Cycle</b>	DC	SSCLK and REFCLK, Pins 5 and 9, measured at VDD/2, CL=15pF	45	50	55	%
<b>Cycle-to-Cycle Jitter</b>	CCJ	SSCLK/REFCLK, Pins 5 and 9	-	125	200	ps
<b>Long Term Jitter</b>	LTJ	REFCLK, Pins 9, 10,000 cycles	-	130	300	ps
<b>Power-up Time (VDD)</b>	tPU1	Time from 0.9VDD to valid frequency at output Pins 5 and 9	-	2.0	5.0	ms
<b>Spread Percent Change Settling Time</b>	tSS%	Time from SSEL0/1 change to stable SSCLK with spread %	-	-	1.0	ms
<b>Modulation Frequency</b>	MF	SSCLK, 100MHz nominal, Pin 5	31	32	33	kHz
<b>Modulation Type and Slew Rate</b>	FMTSR	SSCLK, Pin 5, Triangular Modulation Profile	-	-	0.125	%/μs

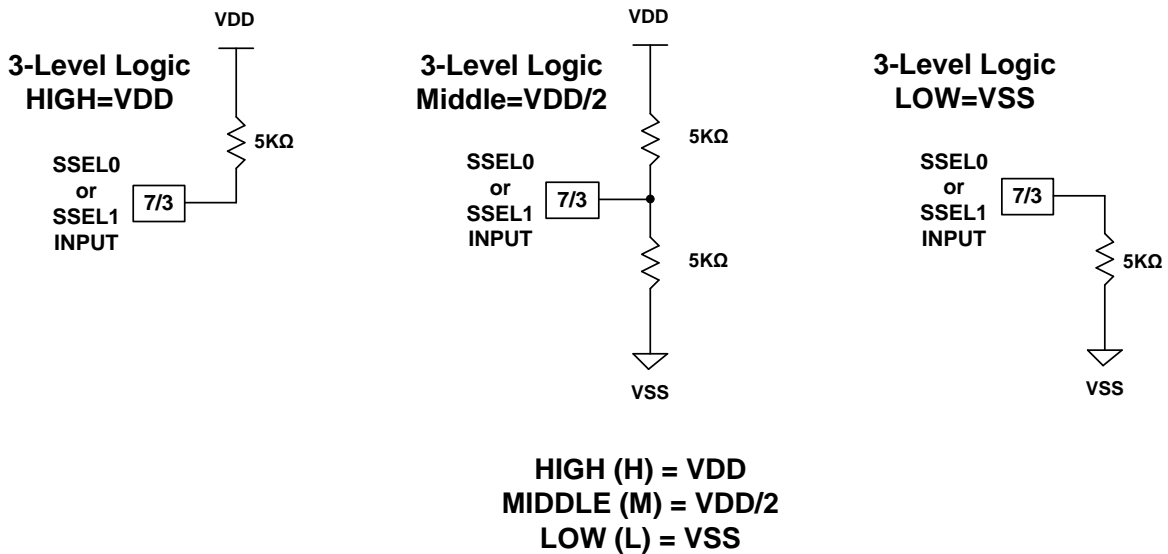
**Table 5. SSEL1 and SSEL0 versus Spread % Selection at SSCLK**

<b>SSEL1 (Pin 3)</b>	<b>SSEL0 (Pin 7)</b>	<b>Spread Percent (%) SSCLK (Pin 5)</b>
Low (VSS)	Low (VSS)	Spread Off (No Spread)
Low (VSS)	Middle (VDD/2)	-0.50%
Low (VSS)	High (VDD)	-2.5%
Middle (VDD/2)	Low (VSS)	-0.25%
Middle (VDD/2)	Middle (VDD/2)	-0.75%
Middle (VDD/2)	High (VDD)	-1.0%
High (VDD)	Low (VSS)	-1.5%
High (VDD)	Middle (VDD/2)	-2.0%
High (VDD)	High (VDD)	-3.0%

**Note: Middle (VDD/2) state requires 5kΩ/5kΩ external resistors as shown in Figure 3, page 5.**

**Table 6. Recommended Crystal Specifications**

Description	Min	Typ	Max	Unit
Nominal Frequency (Fundamental Crystal)	-	27.000	-	MHz
Crystal Accuracy	-	+/-10	-	ppm
Load Capacitance	8	12	18	pF
Shunt Capacitance	-	-	7.0	pF
Equivalent Series Resistance (ESR)	-	-	30	$\Omega$
Drive Level	-	-	1.0	mW



**Figure 3. FSEL0 and FSEL1 Spread % Selection Logic**

**Note:** SSEL0 and SSEL1 pins use 3-Level L(LOW) = VSS, M(MIDDLE)=VDD/2 and H(HIGH) = VDD 3-Level logic to provide 9 spread % values at SSCLK (pin 5) as given in Table 5.

Use 5k $\Omega$ /5k $\Omega$  external resistor divider at SSEL0 and SSEL1 pins from VDD to VSS to obtain VDD/2 for M=VDD/2 Logic level as shown above in Figure 3.

## External Components and Design Considerations

### Typical Application Circuit

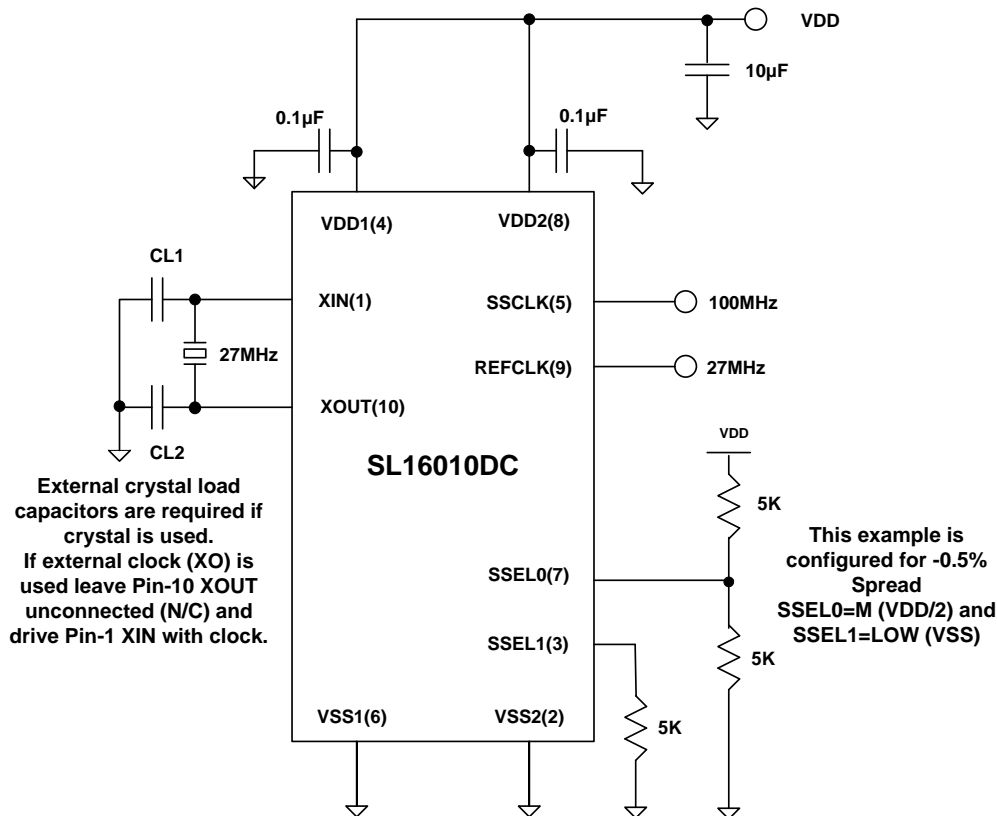


Figure 4. Typical Application Schematic

#### Comments and Recommendations

**Crystal and Crystal Load:** Only use a parallel resonant fundamental AT cut crystal. DO NOT USE higher overtone crystals. To meet the crystal initial accuracy specification (in ppm) make sure that external crystal load capacitor is matched to crystal load specification. To determine the value of CL1 and CL2, use the following formula;

$$C1 = C2 = 2CL - (Cpin + Cp)$$

Where: CL is load capacitance stated by crystal manufacturer

Cpin is the SL16010 pin capacitance (4pF)

Cp is the parasitic capacitance of the PCB traces.

**EXAMPLE;** if a crystal with CL=12pF specification is used and Cp=1pF (parasitic PCB capacitance on PCB), 19 or 20pF external capacitors from pins XIN (pin-1) and XOUT (Pin-10) to VSS are required since CXIN=CXOUT=4pF for the SL16010DC product. Users must verify Cp value.

**Decoupling Capacitor:** A decoupling capacitor of 0.1µF must be used between VDD1/2 pins and VSS1/2 pin. Place the capacitor on the component side of the PCB as close to the VDD1/2 pins as possible. The PCB trace to the VDD1/2 pins and to the VSS via should be kept as short as possible Do not use vias between the decoupling capacitor and the VDD1/2 pins. In addition, a 10uf capacitor should be placed between VDD and VSS.

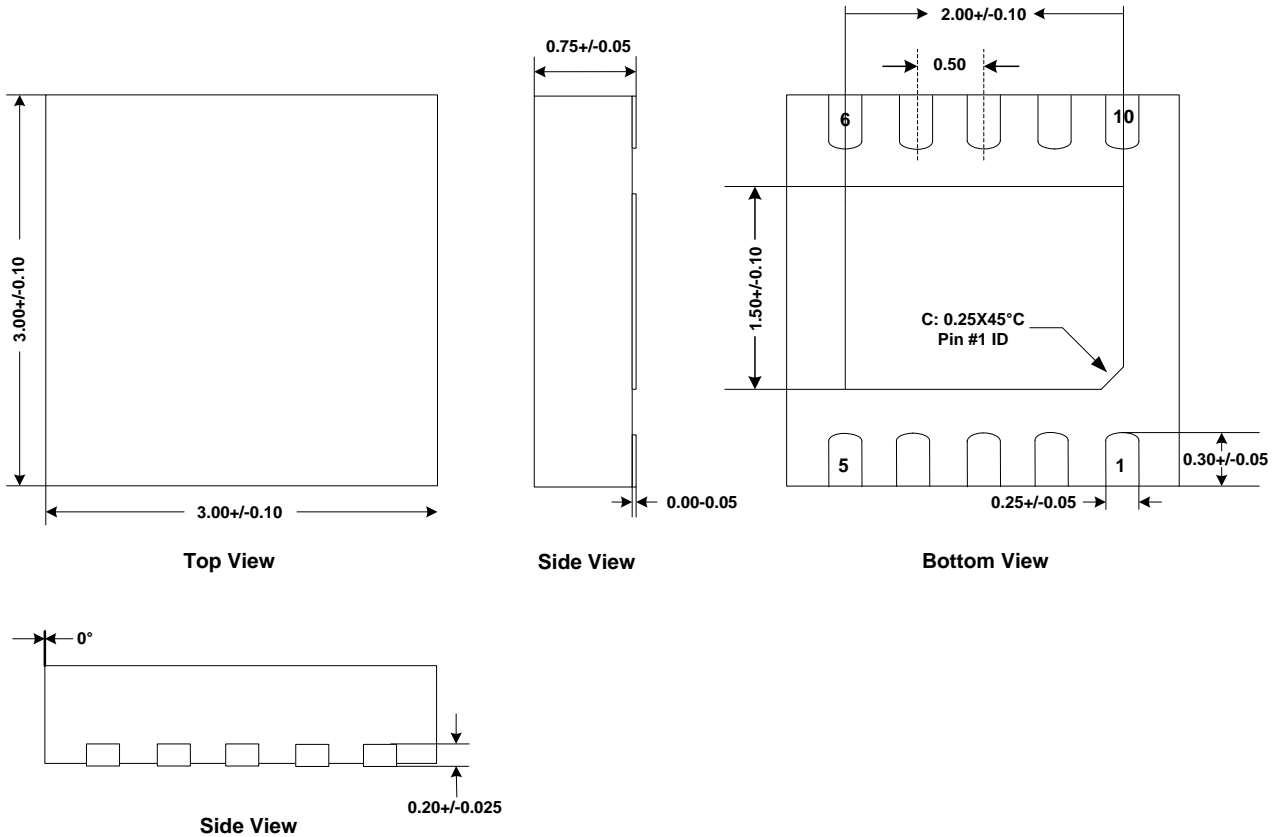
**Series Termination Resistor:** A series termination resistor is recommended if the distance between the outputs (REFCLK and SSCLK) and the load if PCB trace is over 1 ½ inch. The nominal impedance of the outputs is about 24 Ω. Use 22 Ω resistors in series with the outputs to terminate 50Ω trace impedance and place 22 Ω resistors as close

to the clock outputs as possible.

**Package Outline and Package Dimensions**

**10-Pin TDFN Package (3x3x0.75 mm)**

Dimensions are in mm



**Table 7. Thermal Characteristics**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Thermal Resistance Junction to Ambient	$\theta_{JA1}$	Still air	-	75	-	$^\circ\text{C/W}$
	$\theta_{JA2}$	1m/s air flow	-	70	-	$^\circ\text{C/W}$
	$\theta_{JA3}$	3m/s air flow	-	55	-	$^\circ\text{C/W}$
Thermal Resistance Junction to Case	$\theta_{JC}$	Independent of air flow	-	25	-	$^\circ\text{C/W}$



**Table 8. Ordering Information**

Ordering Number	Marking	Shipping Package	Package	Temperature
SL16010DC	SL16010DC	Tube	10-pin TDFN	-10 to 85°C
SL16010DCT	SL16010DC	Tape and Reel	10-pin TDFN	-10 to 85°C

**Note:**

- SL16010DC is RoHS compliant and Halogen Free.**

Product Revisions History

Revision	Date	Originator	Description
Rev 0.5	12/12/2009	C. Ozdalga	Original.
Rev 1.0	1/30/2009	C. Ozdalga	Reduce IDD-max to 18 mA from 28 mA. Change Cxin/Cxot from 4 pF to 6 pF. Change R/R divider from 10Ω/10kΩ to 5kΩ/5kΩ. Add Pull-down resistors definition for SSEL0/1 pins on Pin Description Table. Improve Typical Application Circuit. Remove LTJ for SSCLK until new specification is obtained from customer.
Rev 1.0	2/23/2009	C. Ozdalga	Change 13.5mA-max to 15mA-typ (Key Features – Page-1)
Rev 2.0	2/30/2009	C. Ozdalga	Final production version revision number change to Rev 2.0.
Rev 2.1	4/14/2009	C. Ozdalga	Correct Page 7 package pin number typing error.
Rev 2.2	4/22/2009	C. Ozdalga	Page 3 CIN1, CXI/CXOUT pin capacitance changed to 4pF-typ from 6pF-typ.
Rev 2.3	9/1/2009	C. Ozdalga	Replace “floating” with “VDD/2” in table 5 on page 4 and add note under the same table 5 for clarification. Redo Figure 3 to clarify 3-Level Logic and add 5KΩ resistor from SSEL1 to VSS in Figure 4 on page 6. Change Table 1 to Table 5 on pin description table page 2 for SSEL1 and SSEL0 rows.
Rev 2.4	9/3/2009	C. Ozdalga	Replace “floating” with “VDD/2” in table 5 on page 4 under SSEL1.
Rev 2.5	6/4/2010	C. Ozdalga	Add clock input specifications. SL16010DC can be driven by an external crystal or clock.
Rev 2.6	8/1/2010	C. Ozdalga	Add Halogen Free, page 8.

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